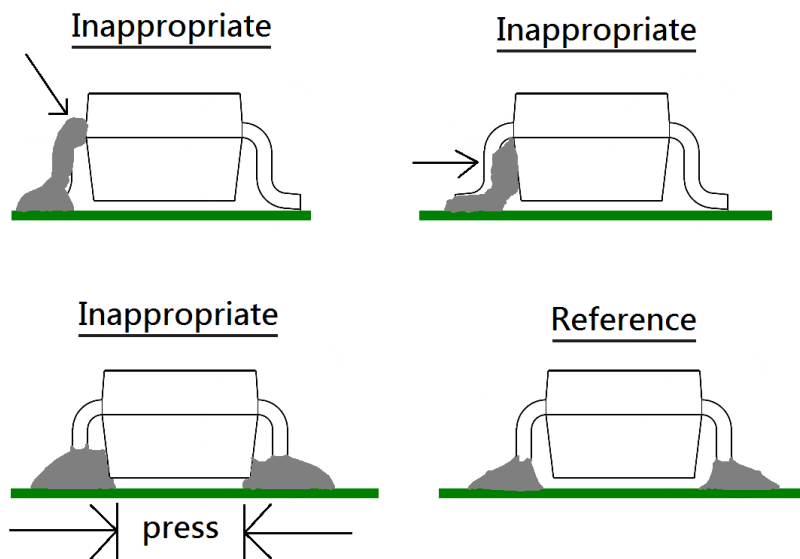


Precautions for the use of Hall Sensor IC

《SMD package》

- Please avoid solder sticking on IC's black body part or filling the space between pins and the black body. Please avoid using too solder, which press the black body on both sides of pins.

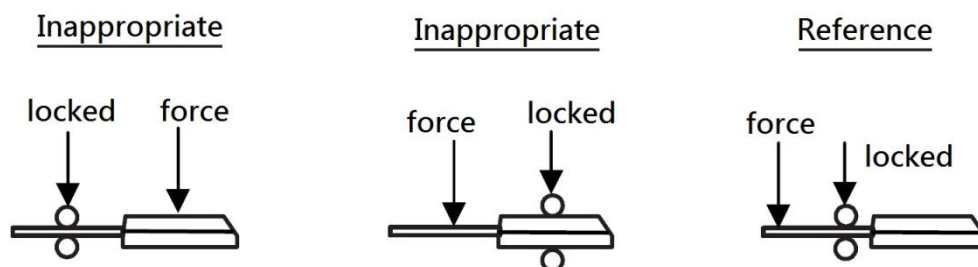


- Please use soft and flexible rubber or silicone as IC's coating. Please avoid using gels that contain corrosive materials.
- IC may suffer stresses when IC's pins deform during processing. It leads to abnormal performance of IC.
- ESD protection of IC during processing is recommended.

《DIP package》

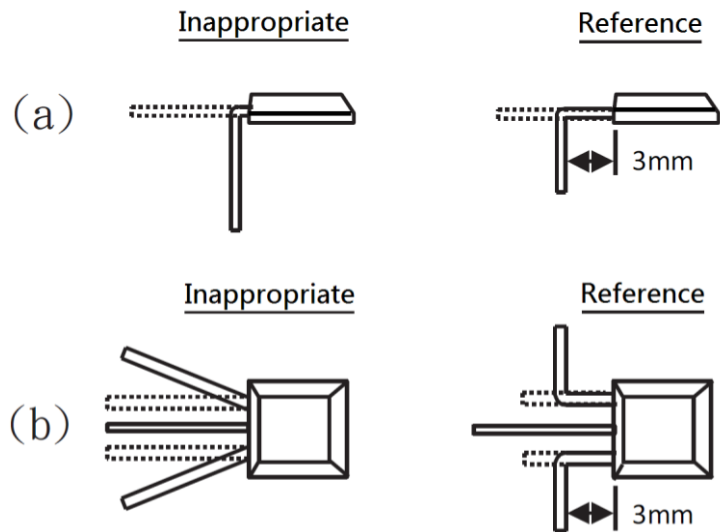
- Please apply force to IC and hold IC on IC's pins, and do not press on the black body part.

《Holding way of IC during production》

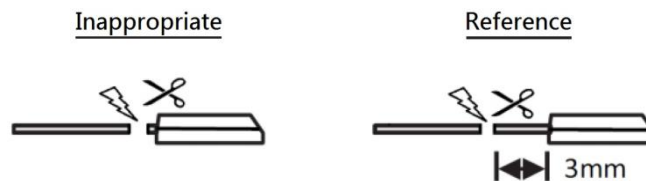


Winson reserves the right to make changes to improve reliability or manufacturability.

《Forming way of pins》



《Pin cutting way》



※ Recommend : Use metal mold to closely locked pins, and do not apply stress on black body of IC during processing. The ideal processing location of IC's pins is at least keeping 3 mm length.

- Please avoid solder sticking on IC's black body part or the junction of pins and black body.

Inappropriate



- Please use soft and flexible rubber or silicone as IC's coating. Please avoid using gels that contain corrosive materials.
- ESD protection of IC during processing is recommended.

Winson reserves the right to make changes to improve reliability or manufacturability.